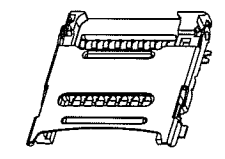
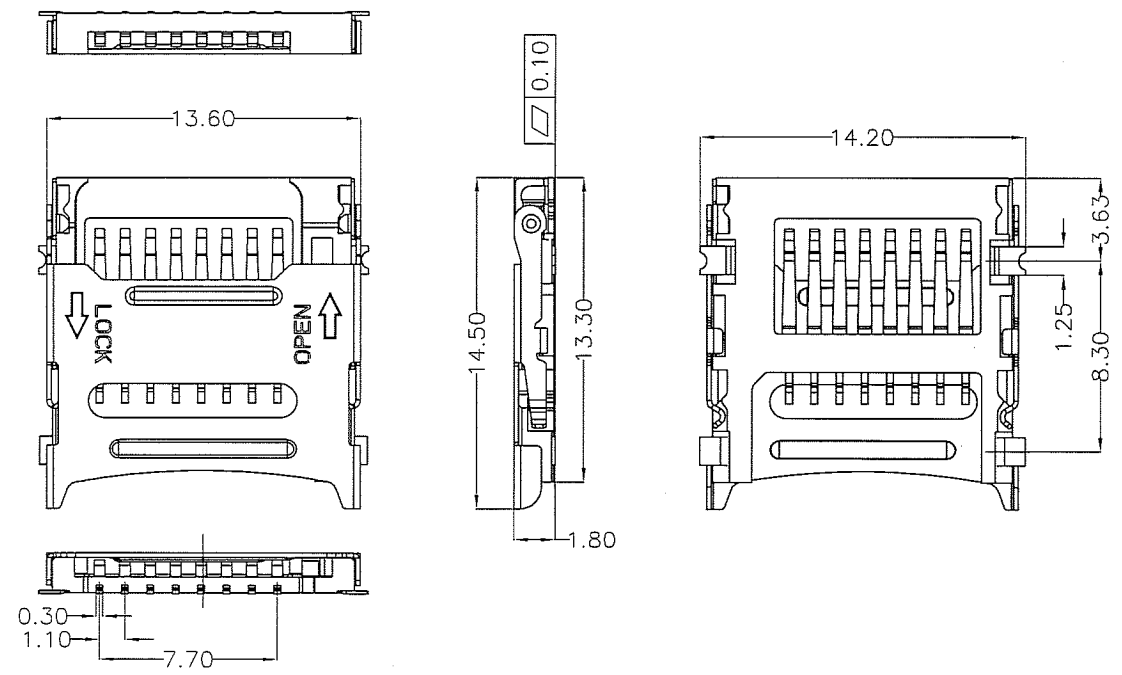


1 2 3 4 5 6 7 8

REV	MODIFICATION	DATE	DRAW
E	EN-09-0814	98.08.18	SAN
F	EN-10-0212	99.02.09	SAN
G	EN-10-0924	99.09.27	SAN

F
E
D
C
B
A



MATERIALS

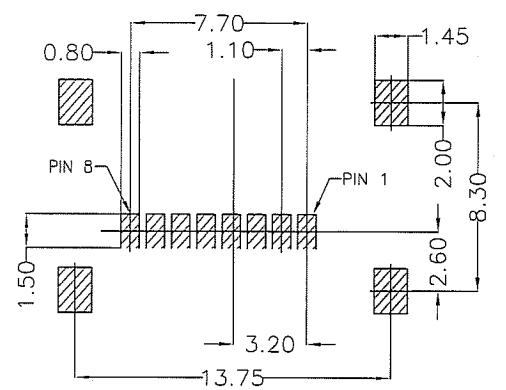
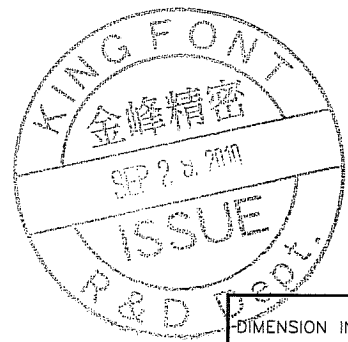
HOUSING: HI-TEMP. PLASTIC (UL 94V-0)
 SHELL: STAINLESS STEEL
 SOLDER PAD: COPPER ALLOY, TIN PLATING
 TERMINAL: COPPER ALLOY, GOLD PLATED ON CONTACT AREA
 TIN PLATING ON SOLDER TAIL

SPECIFICATION

CURRENT RATING: 0.5 AMP MAX
 DIELECTRIC WITHSTANDING: 500V AC FOR ONE MINUTE
 CONTACT RESISTANCE: 100m OHMS MAX
 INSULATION RESISTANCE: 1000M OHMS MIN AT DC 500V
 OPERATION TEMPERATURE: -20°C~+60°C

ORDER INFORMATION:

TFDMF-108 XX B I 00
 PLATING COMPLY TO RoHS
 01:GOLD FLASH
 05:5u" GOLD



P.C.B LAYOUT
TOP VIEW ±0.05

PIN NO.	PIN Assignmeng.
PIN1	DAT2
PIN2	CD/DAT3
PIN3	CMD
PIN4	VDD
PIN5	CLK
PIN6	Uss2
PIN7	DATO
PIN8	DAT1

DIMENSION IN mm [Inch]		PROD. SPEC.	C KINGFONT KINGFONT PRECISION INDUSTRIAL CO., LTD.	
TOLERANCE UNLESS OTHERWISE SPECIFIED		PKG. SPEC.	TITLE TRANS FLASH CARD CONNECTOR HINGE TYPE CUSTOMER DRAWING	
.X±0.30	.X'±	APPROVE <i>Gomy</i>	FILE NO.	DWG NO. TFDMF-108XXBT00
.XX±0.20	.X'±	CHECK <i>Tay</i>	SIZE A4	PROJ. SHEET 1 / 1
.XXX±0.10	.XX'±	DRAW <i>Sam</i>	SCALE 3:1	REV G

1 2 3 4 5 6 7 8 8F-06-R02